REMARKS/ARGUMENTS

The Office Action has been carefully considered. The issues raised are traversed and addressed below with reference to the relevant headings and paragraph numbers appearing under the Detailed Action of the Office Action.

Specification

As requested by the Examiner, the specification has been amended on page 6 line 12 to replace Figure 20 with Figure 7 and in line 18 to replace actors with factors. In addition to this, page 9 line 24 has been corrected to replace the duplicated reference numeral 102 with the correct reference numeral 104. Replacement pages are provided.

"Claim Objections"

In view of the objections raised in paragraph 5 of the Office Action, claims 1 and 12 have been amended as suggested by the Examiner.

"Claim Rejections - 35 USC §102"

In paragraph 7 of the Office Action the Examiner has objected to the claims as being anticipated by Han et al. We respectfully submit that this is not the case.

In particular, claim 1 includes the requirement that the first cap is bonded to the semiconductor chip 16 at the wafer stage prior to separation of the wafer into individual packages or chips. This is not taught or suggested anywhere in Han et al and in view of this, we believe that claim 1 is novel and inventive over the cited document.

In order to further highlight this distinction over the prior art new claims 13 to 19 have been added to the application to further describe the techniques which are used to form the optical fiber terminator package of claim 1.

In particular, claim 13 steps out the steps by which an optical fiber terminator package are formed. These include the steps of molding a sheet to form a number of hollow caps as described for example on page 9, lines 20 to 23. In step (b) the caps are aligned with a wafer which includes a number of semiconductor chips thereon as described for example on page 11, lines 1 to 2.

In step (c) the chips are binded to the wafer as described for example on page 11, lines 2 to 5 before the wafer is separated into individual packages as described for example on page 11, lines 15 to 31.

Again, as mentioned above with respect to claim 1 the process of applying the caps to a wafer which is then subsequently separated, is not taught or suggested Han et al. In view of this, we believe that the claims are novel and inventive over the cited prior art.

Additional dependent claims have also been provided. In particular claims 14 to 19 relate to a variety of features of the processor for molding the sheet as set out for example on page 9 line 8 to page 11 line 7. We respectfully submit that these additional dependant claims provide further distinctions over the cited prior art.

In light of the above, it is respectfully submitted that the objections and claim rejections have been successfully traversed and addressed. The amendments do not involve adding any information that was not already disclosed in the specification, and therefore no new matter is added. Accordingly, it is respectfully submitted that the claims 1 to 19, and the application as a whole with these claims, are allowable, and a favourable reconsideration is therefore earnestly solicited.

Very respectfully.

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September 16, 2003

Assistant Commissioner for Patents
Washington, District of Columbia 20231
USA

Dear Sir

United States Patent Application Serial No. 10/040,405
Inventors/Assignors: KIA SILVERBROOK
Assignee: SILVERBROOK RESEARCH PTY LTD
Title: "Wafer Scale Fiber Optic Termination"
Our Ref: WSM010US

The status of the above application has changed from "Small Entity" to "Large Entity".

Please update your records accordingly.

Yours faithfully

Kia Silverbrook